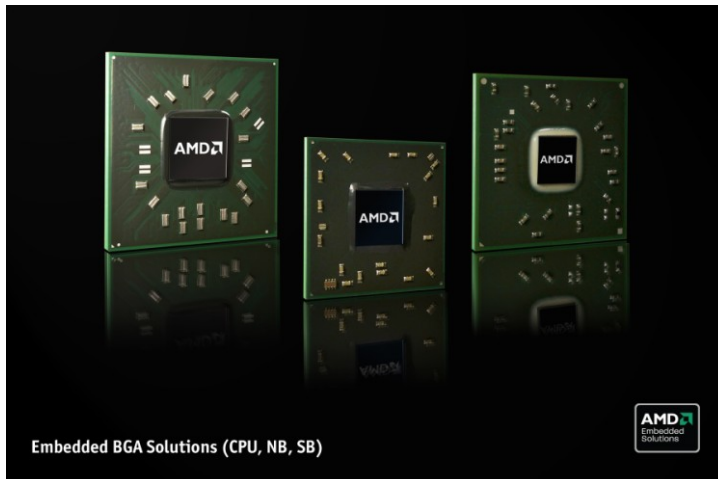


AMD Launches New Complete Platforms for Embedded Systems

Low-power, high-performance CPUs, chipsets and graphics deliver numerous new technical options, benefits of x86, and ease of a single source



SAN JOSE, Calif. — May 5, 2010 — At Embedded Systems Conference today, AMD (NYSE: AMD) announced two new complete platforms for the embedded market, the compact [ASB2 platform](#) (BGA) and the high-performance [AM3 platform](#), that offer myriad combinations of power and performance with up to 74 percent improvement in performance-per-watt over previous generations.* AMD's new flexible embedded platforms consist of chipset and graphics solutions along with high-performance CPUs as low as 8W TDP for the ideal solution based on [application requirements](#). System designers focusing on their next-generation products can see immediate benefits commonly associated with industry-standard x86 processors, including streamlined design and development, a large software ecosystem, and fast time-to-market.

“The barriers to widespread adoption of x86 in the broad embedded market have traditionally been a combination of power, price and the physical footprint of the silicon,” said Buddy Broeker, director, Embedded Solutions Division, AMD. “AMD's embedded solutions have been steadily driving down those barriers while adding enterprise-class performance and features that may not have been readily available to designers in the past. Our commitment to the



embedded market grows stronger as we look to a future introduction of AMD Fusion™ technology products into the embedded space.”

Embedded industry leaders support the benefits of AMD’s approach to x86 and complete platform solutions in the market. Read what customers [iBASE](#) and [Quixant](#) have to say about [AMD Embedded Solutions](#).

New Platform Features

- Faster memory with support for 2 channels DDR3
- Improved I/O for high-throughput and real-time applications with available HyperTransport™ 3.0 technology
- ECC for high-reliability applications like SMB/SOHO storage systems
- Multiple CPU options that offer wide choice of performance and power
 - Power envelopes in 8, 12, 15, 25, 45, and 65 watts TDP
 - Single-, dual- and quad-core
 - Up to 2.8 GHz
- AMD 785E chipset with support for PCI Express® 2.0
- New ATI Radeon™ HD 4200 graphics with DirectX® 10.1, full 1080p display resolution support, HDMI, and power-savings capability with options to support multiple displays
- Socket AM3 package, compatible with socket AM2 when using DDR2 memory for increased design flexibility and scalability
- Lidless BGA package offers low-cost to manufacture, high reliability, and low z-height for small form factors and fan-less designs

The processor variants, each of which is combined with the AMD785E / SB850M chipsets and which support the Direct Connect Architecture for a simplified board design, are available on the ASB2 platform of the AMD Turion™ II Neo single-core processor at 1.0 GHz up to the AMD Turion™ II Neo dual-core processor at 2.2 GHz. The AM3 platform is scalable from the Athlon II XLT Dual Core processor with 2.0 GHz up to the AMD Phenom™ II XLT Quad-Core Processor (2.2 GHz). In total, 9 performance classes were launched alongside the AMD785E, all of which support 64-bit:

ASB2 (rugged BGA platform)

- 25W AMD Turion™ II Neo (Dual-Core, 2.2GHz, HT3)
- 15W AMD Turion II Neo (Dual-Core, 1.5 GHz, HT3)
- 12W AMD Athlon II Neo (Dual-Core, 1.3 GHz, HT1)



- 12W AMD Athlon II Neo (Single-Core, 1.7 GHz, HT1)
- 8W AMD Athlon II Neo (Single-Core, 1.0 GHz, HT1)

AM3 (socketed platforms)

- 65W AMD Phenom™ II XLT (Quad-Core, 2.2GHz, HT3)
- 45W AMD Athlon II XL (Dual-Core, 2.8GHz, HT3)
- 45W AMD Athlon II XLT (Dual-Core, 2.7GHz, HT3)
- 25W AMD Athlon II XLT (Dual-Core, 2.0 GHz, HT3)

* Internal testing of current vs. previous generation AMD processor-based embedded systems as of April 1, 2010, showed up to 74% performance-per-watt advantage for the current generation. Current system: AMD Athlon™ II Neo R34L (8W TDP), Bimini development platform, AMD 785 Chipset, 2 GB RAM, Windows XP SP2. Previous generation: AMD Sempron™ 2010U processor (15W TDP), MSI 9858 motherboard, 2 GB RAM, Windows XP SP2. Performance-per-watt calculated based on geometric mean of three benchmarks divided by processor thermal design power (TDP). Benchmarks: 3DMark®06; POV-Ray; and SiSoftware Sandra 2007 (Processor Arithmetic, Memory Bandwidth, and Performance Index subtests).

Supporting Resources

[iBASE guest blog post](#)

[Quixant guest blog post](#)

[AMD@Work blog](#)

[Press presentation](#)

[Photos](#)



About AMD

Advanced Micro Devices (NYSE: AMD) is an innovative technology company dedicated to collaborating with customers and technology partners to ignite the next generation of computing and graphics solutions at work, home and play. For more information, visit <http://www.amd.com>.

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